



/ Revised record

A	2020.02	ALL	SI2301 BRCS2301MA		
B	2020.03.10	1 2	1. " " 2.		
C	2020-5-15	1			
D	2021-12-3	3	CISS COSS CRSS		
A	2022-6-20	all	Q AEC-Q101 , H Q 245±5°C 5± 0.5sec 255± 5°C 5±0.5sec		

/ Descriptions

SOT-23 塑封封装 P 道 MOS 场效应管。

P- CHANNEL MOSFET in a SOT-23 Plastic Package.

/ Features

芯片采用超高密度元胞设计技术, $R_{DS(ON)}$ 导通电阻小, SOT-23 封装, 符合 AEC-Q101 标准高可靠性要求, 无卤产品。

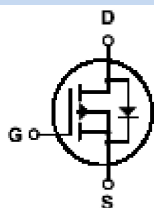
Super high dense cell design for low $R_{DS(ON)}$, SOT-23 package, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

/ Applications

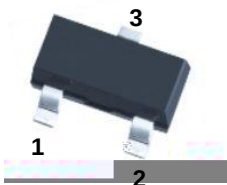
主要用于显示屏驱动, 满足汽车应用的严格要求。

Primarily the display screen drive applications, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit



/ Pinning



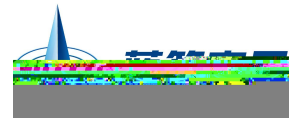
PIN1 : G

PIN 2 : S

PIN 3 : D

/ Marking

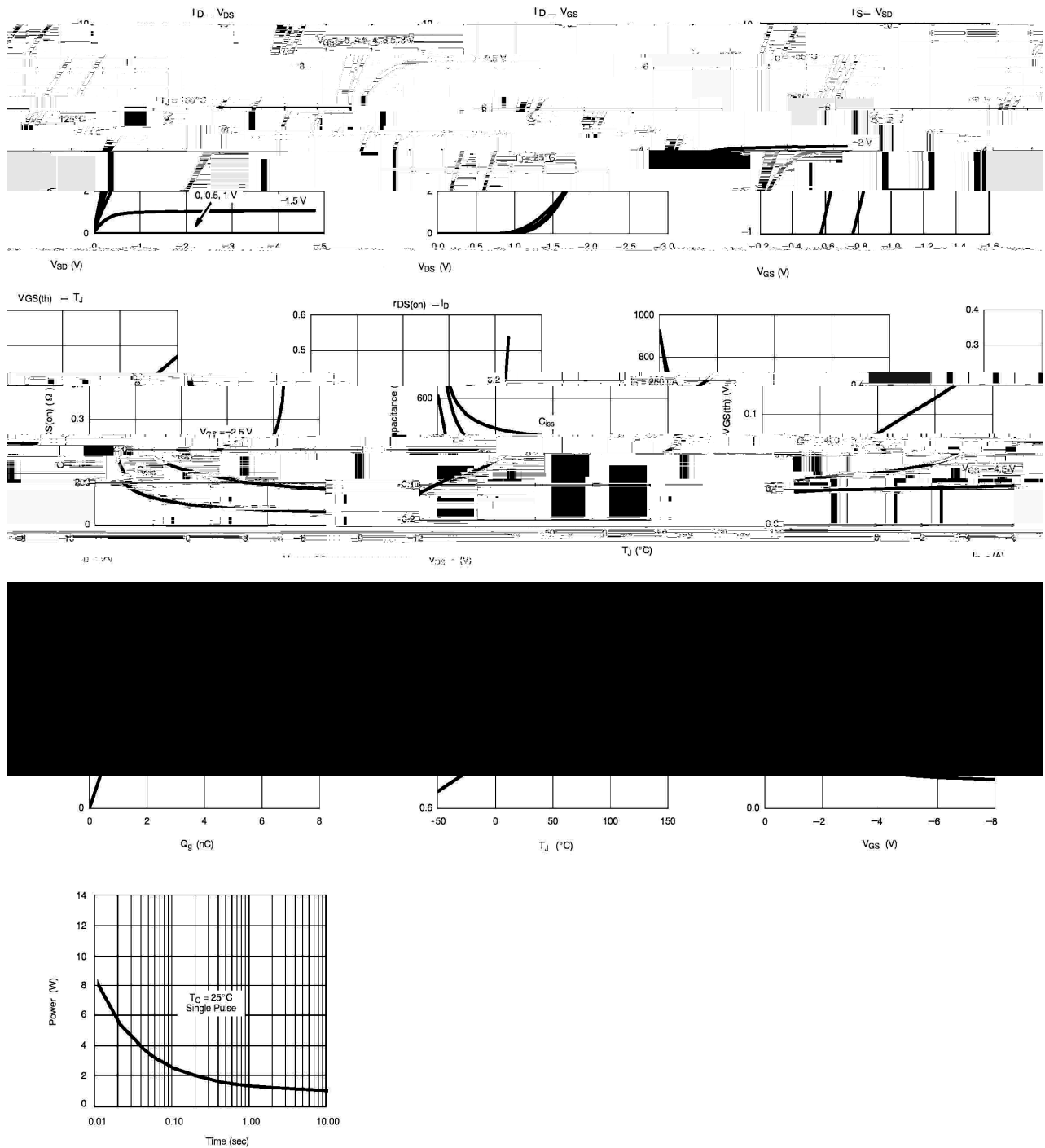
Marking	A1Q
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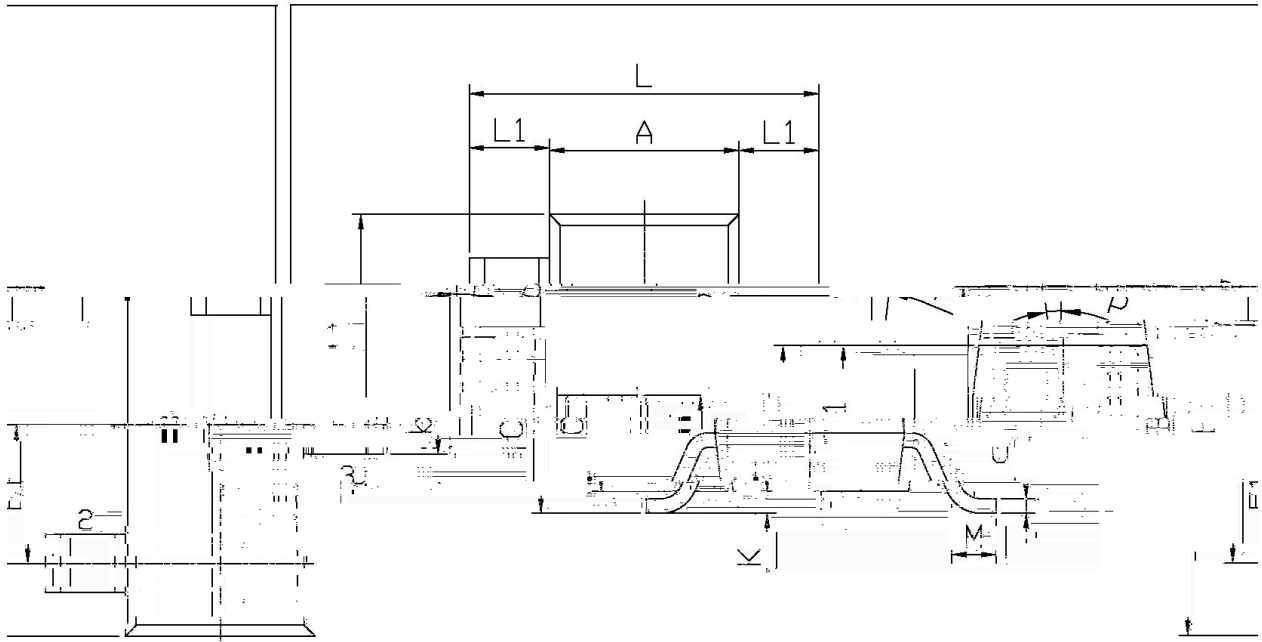
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	-20	V



/ Electrical Characteristic Curve



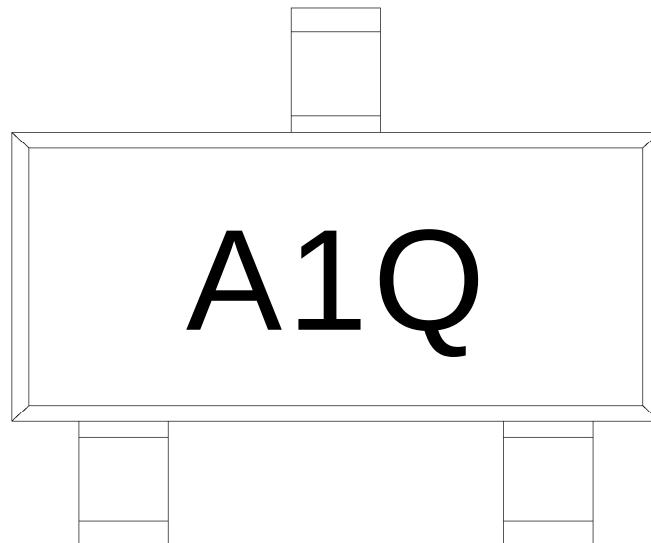
/ Package Dimensions



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10

0.20MIN	0.10	0.10	0.10
7°	0.85	1.05	P
	0.35	0.55	

/ Marking Instructions



说明：

A1: 为型号代码

Q: 为汽车无卤产品标识

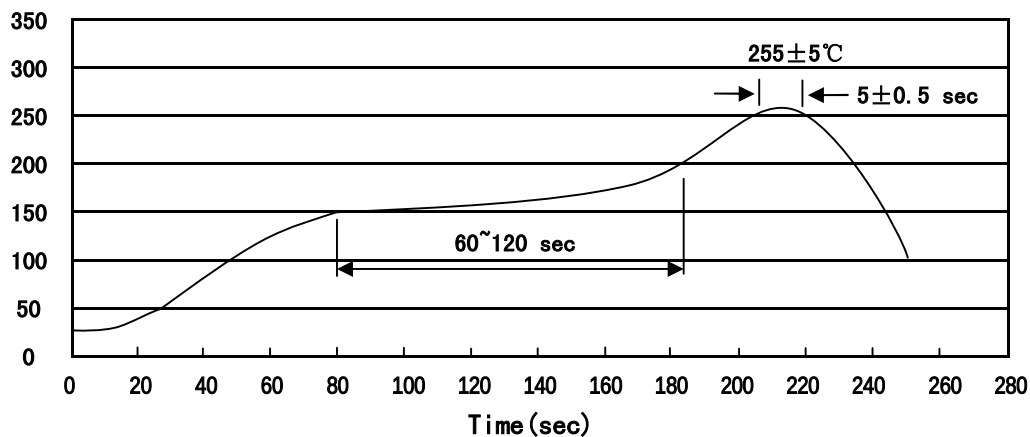
Note:

A1 : Product Type

Q: Automobile halogen-free product Code



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1 150 200 60 120sec; 1.Preheating:150~200°C, Time:60~120sec.
- 2 255±5 5±0.5sec; 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
- 3 2 10°C/sec. 3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

260±5°C

10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices